HOSTAFORM® C 9021 SW XAP®2 LS

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM-KD10
Molding compound ISO 29988-POM-K,KD10,GLNRS2,3-2
POM copolymer Injection molding type, special modified with anti-friction additives for prevention of squeaking noise; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Ranges of applications: For sliding combinations with low wear and low coefficient of friction, prevents squeaking noise. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1,5 mm. Reduced emission grade. Emissions according to VDA 275 < 5 mg/kg Preliminary Datasheet

Product information

Resin Identification	POM-KD10	ISO 1043
Part Marking Code	>POM-KD10<	ISO 11469

Rheological properties

Melt volume-flow rate	7	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	

Typical mechanical properties

Tensile modulus	392000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	7500	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7	%	ISO 527-1/-2
Nominal strain at break	16	%	ISO 527-1/-2
Flexural modulus	377000	psi	ISO 178
Flexural strength	9140	psi	ISO 178
Charpy impact strength, 23°C	42.8	ftlb/in^2	ISO 179/1eU
Charpy impact strength, -30°C	40.4	ftlb/in^2	ISO 179/1eU
Charpy notched impact strength, 23°C	1.9	ftlb/in^2	ISO 179/1eA
Charpy notched impact strength, -30°C	1.9	ftlb/in^2	ISO 179/1eA
Ball indentation hardness, H 358/30	19600	psi	ISO 2039-1

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	176	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.67	E-4/°F	ISO 11359-1/-2

Flammability

FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 2 mm	2.32	in/min	ISO 3795 (FMVSS 302)

Physical/Other properties

Density	0.0513	lb/in^3	ISO 1183

HOSTAFORM® C 9021 SW XAP®2 LS
HOSTAFORM®

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	392	°F
Min. melt temperature	374	°F
Max. melt temperature	410	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	$2h^2$-3	s
Back pressure	290	psi

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF

Characteristics

Processing	Injection Molding, Other Extrusion
Additives	Release agent
Special characteristics	U.V. stabilized or stable to weather, Low wear / Low friction, Low emissions

Additional information

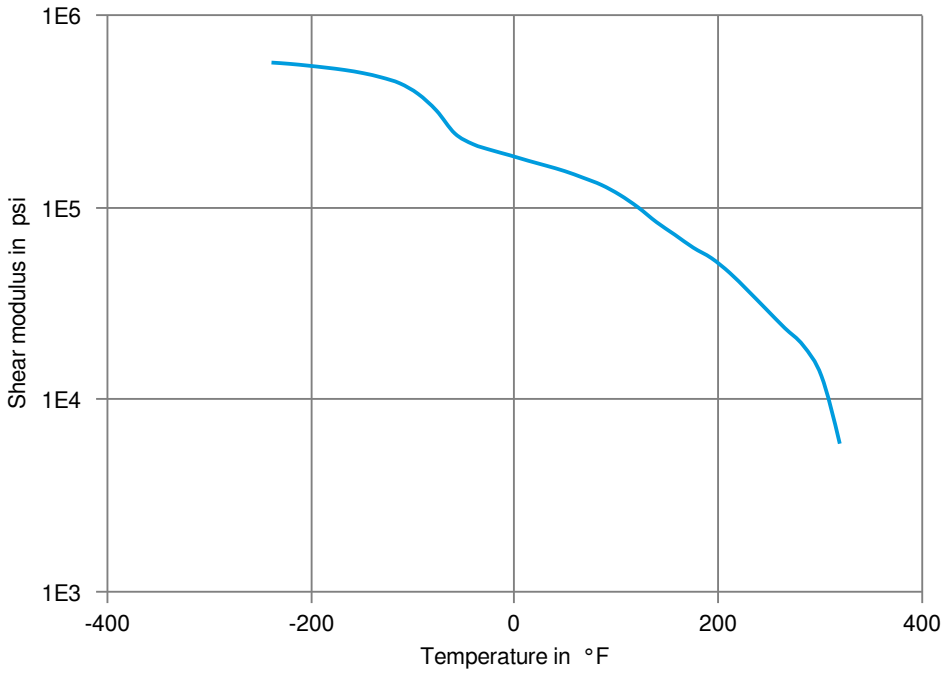
Processing Notes

Storage

The product can then be stored in standard conditions until processed.

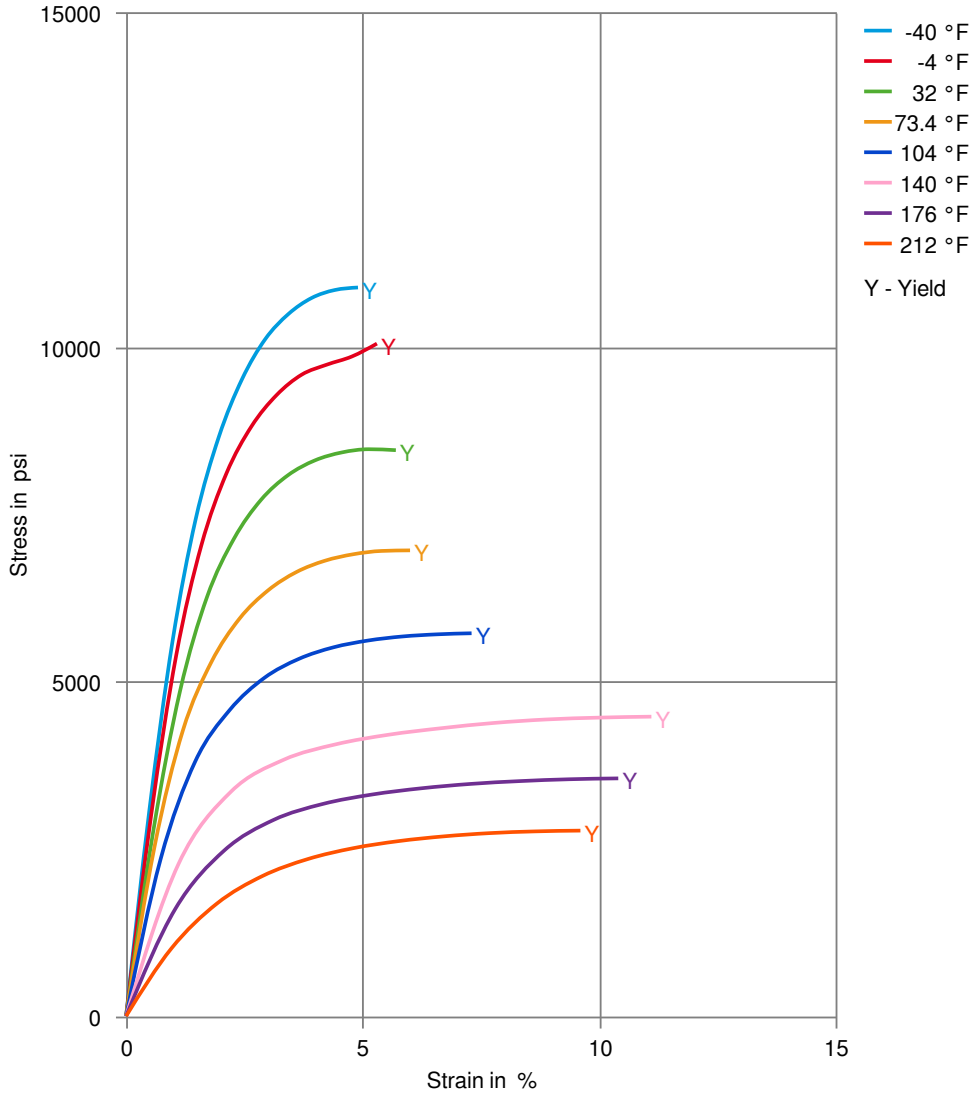
HOSTAFORM® C 9021 SW XAP®2 LS
HOSTAFORM®

Dynamic Shear modulus-temperature



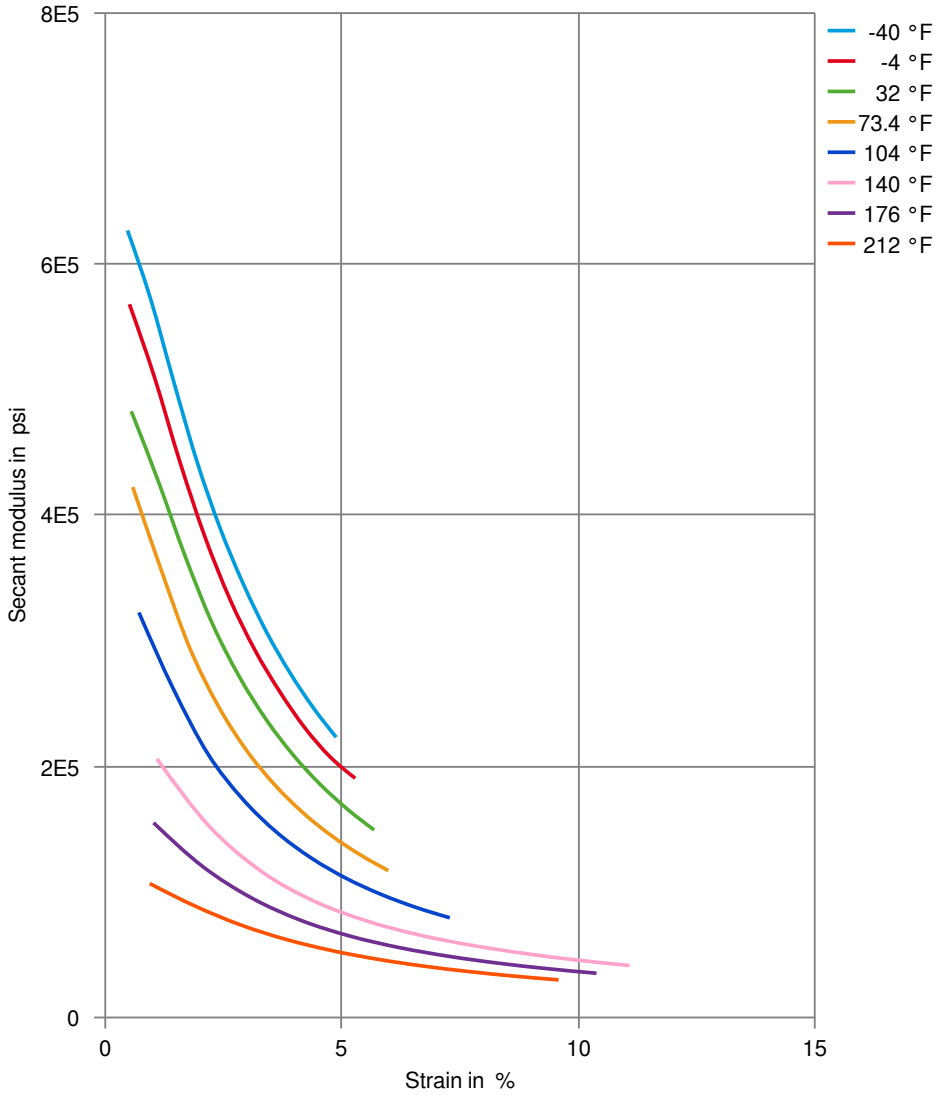
HOSTAFORM® C 9021 SW XAP®2 LS
HOSTAFORM®

Stress-strain



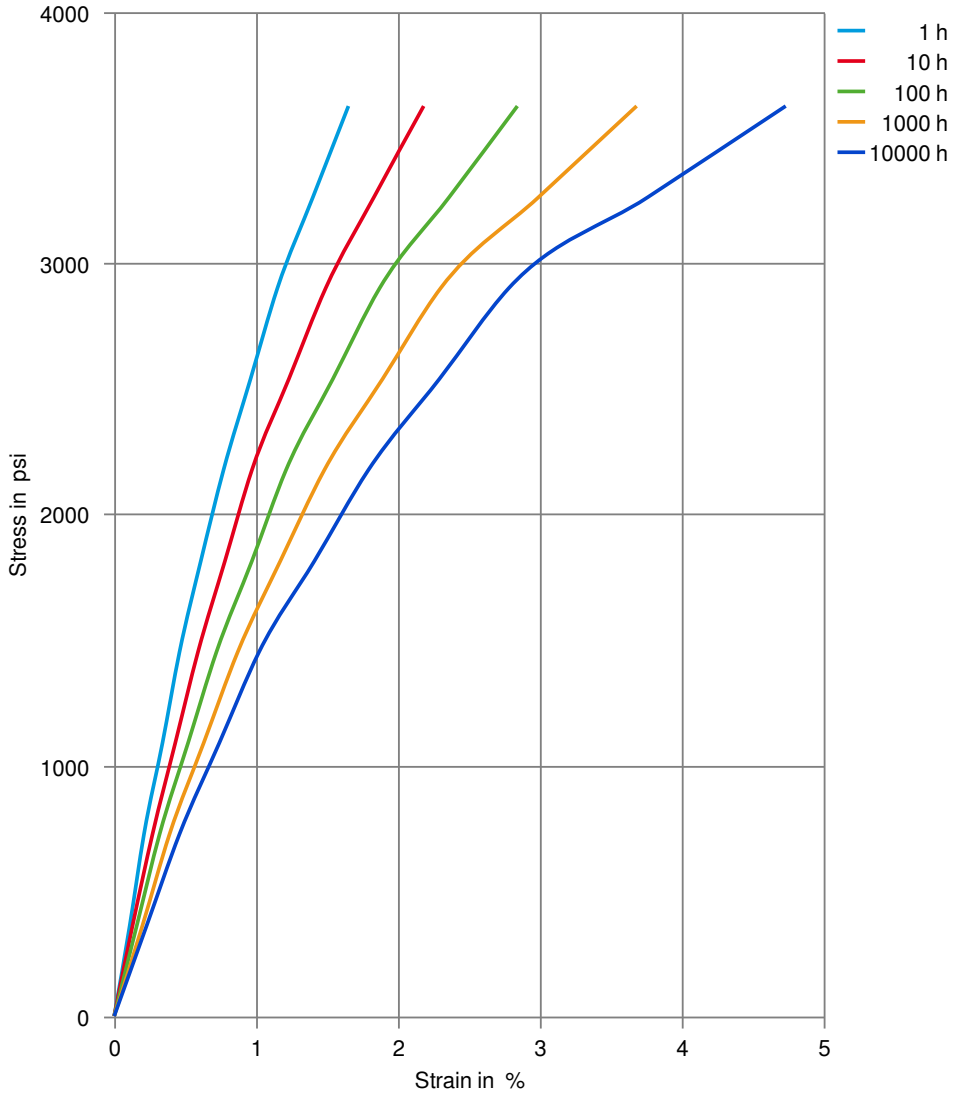
HOSTAFORM® C 9021 SW XAP®2 LS
HOSTAFORM®

Secant modulus-strain



HOSTAFORM® C 9021 SW XAP®2 LS
HOSTAFORM®

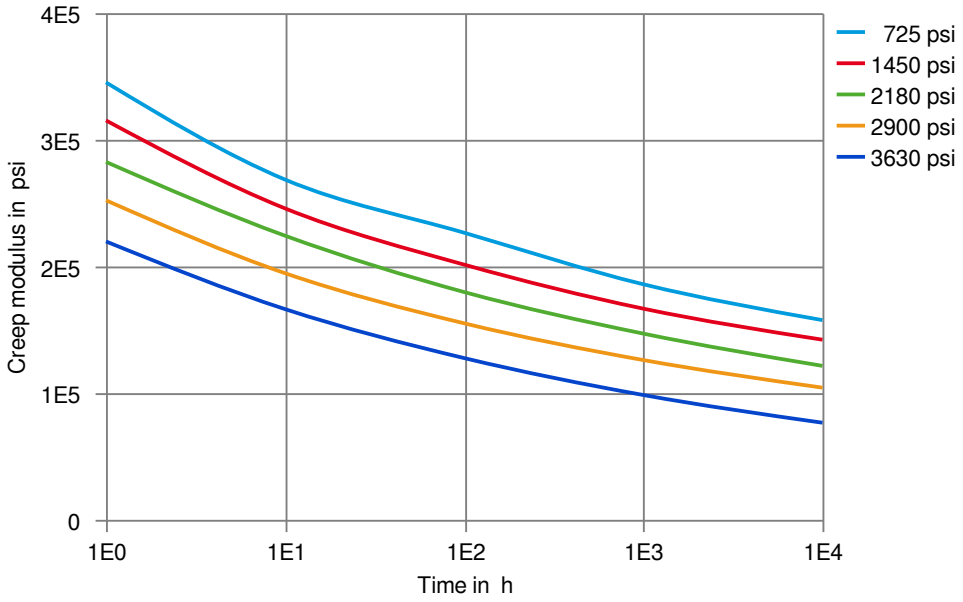
Stress-strain (isochronous) 73.4 °F



HOSTAFORM® C 9021 SW XAP®2 LS

HOSTAFORM®

Creep modulus-time 73.4 °F



Revised: 2026-08-12 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colorants or other additives may cause significant variations in data values. Properties of molded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.
Copyright © 2026 Celanese or its affiliates. All rights reserved.
Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates.